

Title (en)
ELECTRONIC CIRCUIT APPARATUS

Title (de)
VORRICHTUNG MIT EINER ELEKTRONISCHEN SCHALTUNG

Title (fr)
APPAREIL À CIRCUIT ÉLECTRONIQUE

Publication
EP 3258749 A1 20171220 (EN)

Application
EP 17165188 A 20170406

Priority
JP 2016121038 A 20160617

Abstract (en)
There is provided an electronic circuit apparatus in which the heat generated at an electronic component can be transferred to a heat spreader efficiently. An electronic circuit apparatus (1) includes a dielectric substrate (10), an electronic component (61, 62), a heat spreader (15), and a conductive via (50). The conductive via (50) electrically and thermally connects the electronic component (61, 62) and the heat spreader (15). The conductive via (50) extends from the first surface (11) to at least an interior of the heat spreader (15) and is in surface-contact with the heat spreader (15).

IPC 8 full level
H05K 1/02 (2006.01); **H05K 1/18** (2006.01); **H05K 3/40** (2006.01)

CPC (source: CN EP US)
H01L 23/13 (2013.01 - US); **H01L 23/3121** (2013.01 - US); **H01L 23/36** (2013.01 - EP); **H01L 23/367** (2013.01 - CN); **H01L 23/3675** (2013.01 - US); **H01L 23/3677** (2013.01 - EP); **H01L 23/49811** (2013.01 - EP US); **H01L 23/5384** (2013.01 - US); **H01L 23/5386** (2013.01 - US); **H01L 24/32** (2013.01 - US); **H01L 25/072** (2013.01 - US); **H01L 25/16** (2013.01 - CN); **H05K 1/0206** (2013.01 - EP US); **H01L 23/66** (2013.01 - EP); **H01L 24/29** (2013.01 - EP); **H01L 24/32** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/73** (2013.01 - EP); **H01L 25/072** (2013.01 - EP); **H01L 2224/29111** (2013.01 - EP); **H01L 2224/29139** (2013.01 - EP); **H01L 2224/29147** (2013.01 - EP); **H01L 2224/2919** (2013.01 - US); **H01L 2224/2929** (2013.01 - EP); **H01L 2224/29339** (2013.01 - EP); **H01L 2224/29347** (2013.01 - EP); **H01L 2224/32225** (2013.01 - US); **H01L 2224/32245** (2013.01 - EP); **H01L 2224/451** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48106** (2013.01 - US); **H01L 2224/48225** (2013.01 - US); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/49175** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/83424** (2013.01 - EP); **H01L 2224/83447** (2013.01 - EP); **H01L 2224/8384** (2013.01 - EP); **H01L 2224/85424** (2013.01 - EP); **H01L 2224/85447** (2013.01 - EP); **H01L 2224/92247** (2013.01 - EP); **H01L 2924/15151** (2013.01 - EP); **H01L 2924/15153** (2013.01 - EP); **H01L 2924/15313** (2013.01 - EP); **H01L 2924/15322** (2013.01 - EP); **H01L 2924/19105** (2013.01 - EP US); **H01L 2924/3512** (2013.01 - EP); **H05K 1/021** (2013.01 - EP US); **H05K 1/181** (2013.01 - EP US); **H05K 3/4053** (2013.01 - EP US); **H05K 2201/09554** (2013.01 - EP US); **H05K 2203/049** (2013.01 - EP US)

Citation (applicant)
JP H0595236 A 19930416 - MATSUSHITA ELECTRIC IND CO LTD

Citation (search report)
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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

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EP 3258749 A1 20171220; CN 107527898 A 20171229; JP 2017224788 A 20171221; US 2017365556 A1 20171221

DOCDB simple family (application)
EP 17165188 A 20170406; CN 201710272070 A 20170424; JP 2016121038 A 20160617; US 201715486403 A 20170413